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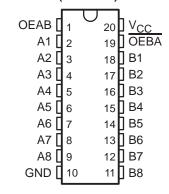
- State-of-the-Art *EPIC-IIB™* BiCMOS Design Significantly Reduces Power Dissipation
- **ESD Protection Exceeds 2000 V Per** MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 500 mA Per **JESD 17**
- Typical V_{OLP} (Output Ground Bounce) < 1 V at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$
- High-Drive Outputs (-32-mA IOH, 64-mA IOI)
- **Package Options Include Plastic** Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), and Plastic (N) and Ceramic (J) DIPs

description

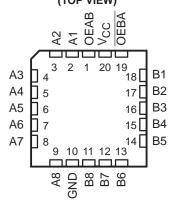
These octal bus transceivers provide for asynchronous communication between data buses. The control-function implementation allows for maximum flexibility in timing. The 'ABT620 devices provide inverted data at the outputs.

These devices allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic levels at the output-enable (OEAB and OEBA) inputs.

SN54ABT620 . . . J PACKAGE SN74ABT620 . . . DB, DW, N, OR PW PACKAGE (TOP VIEW)



SN54ABT620 . . . FK PACKAGE (TOP VIEW)



The output-enable inputs can be used to disable the device so that the buses are effectively isolated. The dual-enable configuration gives the transceivers the capability of storing data by simultaneously enabling OEAB and OEBA. When both OEAB and OEBA are enabled and all other data sources to the two sets of bus lines are at high impedance, both sets of bus lines (16 total) remain at their last states. In this way, each output reinforces its input in this configuration.

To ensure the high-impedance state during power up or power down, OEBA should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver. OEAB should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver.

The SN54ABT620 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT620 is characterized for operation from -40°C to 85°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

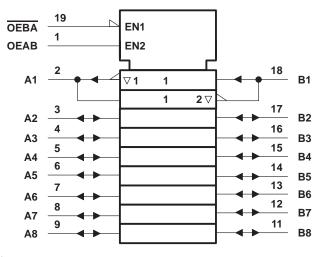
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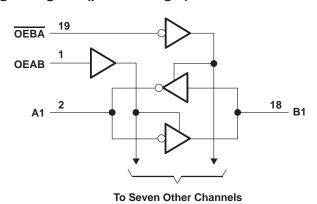
FUNCTION TABLE

INP	UTS	OPERATION
OEBA	OEAB	OPERATION
L	L	B data to A bus
L	Н	B data to A bus, A data to B bus
Н	L	Isolation
Н	Н	A data to B bus

logic symbol†



logic diagram (positive logic)



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V _{CC}	
Input voltage range, V _I (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high or	power-off state, V _O –0.5 V to 5.5 V
Current into any output in the low state, IO: SN54	4ABT620 96 mA
SN74	4ABT620 128 mA
Input clamp current, I _{IK} (V _I < 0)	
Output clamp current, I _{OK} (V _O < 0)	
Package thermal impedance, θ _{JA} (see Note 2): D	DB package 115°C/W
D	DW package 97°C/W
N	I package 67°C/W
P	PW package 128°C/W
Storage temperature range, T _{stq}	

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.



^{2.} The package thermal impedance is calculated in accordance with JESD 51, except for through-hole packages, which use a trace length of zero.

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recommended operating conditions (see Note 3)

			SN54A	BT620	SN74A	BT620	UNIT
			MIN	MAX	MIN	MAX	UNIT
VCC	Supply voltage		4.5	5.5	4.5	5.5	V
VIH	High-level input voltage		2	EW	2		V
VIL	Low-level input voltage			0.8		0.8	V
VI	Input voltage		0 <	Vcc	0	VCC	V
IOH	High-level output current		, ()	-24		-32	mA
loL	Low-level output current		200	48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled	A.	5		5	ns/V
TA	Operating free-air temperature		<i>–</i> 55	125	-40	85	°C

NOTE 3: All unused pins (control or I/O) of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

SN54ABT620, SN74ABT620 OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CON	Т	A = 25°C	;	SN54A	BT620	SN74A	BT620	UNIT	
PAI	RAMETER	TEST CON	CMOITIUIS	MIN	TYP†	MAX	MIN	MAX	MIN	MAX	UNII
VIK		V _{CC} = 4.5 V,	I _I = -18 mA			-1.2		-1.2		-1.2	V
		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$	2.5			2.5		2.5		
\/~		$V_{CC} = 5 V$,	$I_{OH} = -3 \text{ mA}$	3			3		3		V
VOH		V _{CC} = 4.5 V	$I_{OH} = -24 \text{ mA}$	2			2				V
		VCC = 4.5 V	$I_{OH} = -32 \text{ mA}$	2*					2		
VOL		V _{CC} = 4.5 V	I _{OL} = 48 mA			0.55		0.55			V
VOL		VCC = 4.5 V	I _{OL} = 64 mA			0.55*				0.55	V
V _{hys}					100						mV
	Control inputs	V _{CC} = 5.5 V,	VI = VCC or GND			±1		±1		±1	μΑ
H	A or B ports	vCC = 5.5 v,	AL = ACC OLGIAD			±100		±100		±100	μΑ
lozh [‡]		$V_{CC} = 5.5 \text{ V},$	V _O = 2.7 V			50		50		50	μΑ
l _{OZL} ‡		$V_{CC} = 5.5 \text{ V},$	V _O = 0.5 V			-50		– 50		-50	μΑ
I _{off}		$V_{CC} = 0$,	V_I or $V_O \le 4.5 \text{ V}$			±100	1	ζ		±100	μΑ
ICEX		V _{CC} = 5.5 V, V _O = 5.5 V	Outputs high			50	2700	50		50	μΑ
IO§		V _{CC} = 5.5 V,	V _O = 2.5 V	-50	-100	-180	– 50	-180	-50	-180	mA
		V _{CC} = 5.5 V,	Outputs high		5	250		250		250	μΑ
Icc	A or B ports	$I_0 = 0$,	Outputs low		24	30		30		30	mA
		$V_I = V_{CC}$ or GND	Outputs disabled		0.5	250		250		250	μΑ
	Data inputs	V _{CC} = 5.5 V, One input at 3.4 V,	Outputs enabled			1.5		1.5		1.5	
ΔICC¶		Other inputs at VCC or GND	Outputs disabled			0.05		0.05		0.05	mA
	Control inputs	$V_{CC} = 5.5 \text{ V}$, One inpute of the original of the contraction o				1.5		1.5		1.5	
Ci	Control inputs	V _I = 2.5 V or 0.5 V			4						pF
C _{io}	A or B ports	V _O = 2.5 V or 0.5 V			7						pF

^{*} On products compliant to MIL-PRF-38535, this parameter does not apply.

[†] All typical values are at $V_{CC} = 5 \text{ V}$.

[‡] The parameters I_{OZH} and I_{OZL} include the input leakage current.

[§] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

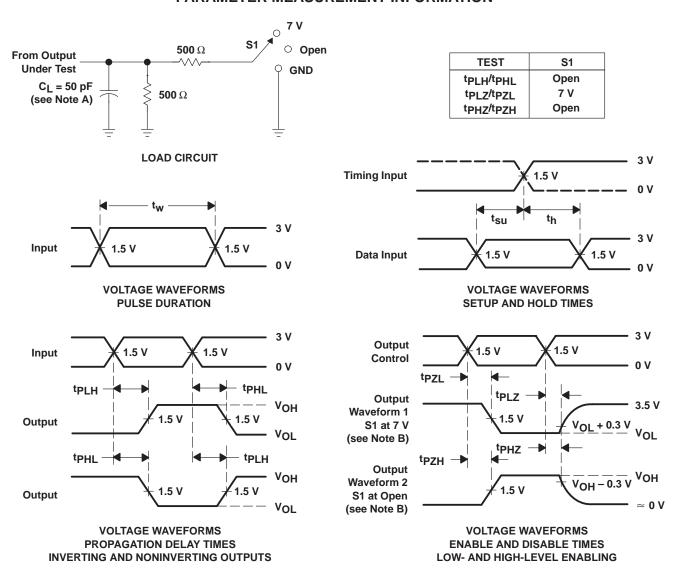
[¶] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

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switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)			= 5 V, 25°C	SN54AE	BT620	SN74A	BT620	UNIT
	(IIVI O1)	(0011 01)	MIN	MAX	MIN	MAX	MIN	MAX	
^t PLH	A or B	B or A	1	4.1	1		1	4.8	ns
^t PHL	AOIB	BOIA	1	4.3	1	4	1	4.8	115
^t PZH	OFD.	А	1.3	4.6	1.3	1/2	1.3	5.5	ns
^t PZL	OEBA	A	1	6.1	1	2	1	7.1	115
^t PHZ	OFD.	А	2	6.3	2	ζ	2	7	20
^t PLZ	OEBA	A	1.4	5.4	1.4		1.4	5.8	ns
^t PZH	OFAR	В	1.6	6.2	1 .6		1.6	6.8	
^t PZL	OEAB	Б	2	5.9	2		2	6.4	ns
^t PHZ	OFAR	В	1.2	5.6	1.2		1.2	6.5	200
t _{PLZ}	OEAB	D	1.1	4.7	1.1		1.1	5.6	ns

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_r \leq 2.5$ ns, $t_f \leq 2.5$ ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms







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PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Top-Side Markings	Samples
SN74ABT620DBLE	OBSOLETE	SSOP	DB	20		TBD	Call TI	Call TI	-40 to 85	()	
SN74ABT620DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT620	Samples
SN74ABT620DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT620	Samples
SN74ABT620DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT620	Samples
SN74ABT620DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT620	Samples
SN74ABT620DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT620	Samples
SN74ABT620DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT620	Samples
SN74ABT620N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	SN74ABT620N	Samples
SN74ABT620NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	SN74ABT620N	Samples
SN74ABT620NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT620	Samples
SN74ABT620NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT620	Samples
SN74ABT620NSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT620	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.



PACKAGE OPTION ADDENDUM

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Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Only one of markings shown within the brackets will appear on the physical device.

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PACKAGE MATERIALS INFORMATION

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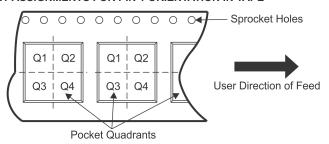
TAPE AND REEL INFORMATION





Α0	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT620DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN74ABT620NSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABT620DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74ABT620NSR	SO	NS	20	2000	367.0	367.0	45.0

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